nexperia

Final Product Change Notification

Issue Date: 19-Mar-2021 Effective Date: 22-Mar-2021 Dear Emma Tempest,

UPDATE

Here's your personalized quality information concerning products Premier Farnell PLC purchased from Nexperia.

For More details Please Contact your respective Nexperia CSR/AM.

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202101001F01U01



Management Summary

UPDATE: In reference to PCN 202101001F01 we herewith inform you that the effective date for the implementation and date of first shipment will be changed to March 22nd, 2021.

CI	na	nge	e Ca	iteg	ory

[] Wafer Fab Process	[X] Assembly	[] Product Marking	[] Test	[] Design
	Process		Location	
[] Wafer Fab Materials	[X] Assembly	[] Mechanical Specification	[]Test	[] Errata
	Materials		Process	
[] Wafer Fab Location	[] Assembly	[]	[] Test	[] Electrical
	Location	Packing/Shipping/Labeling	Equipment	spec./Test
				coverage

2nd source Polyimide material

Details of this Change

Use of Asahi Kasei Corporation BL-301 polyimide in addition to current HD MicroSystems HD4100 material as dielectric layer for solder bumping at locations JCAP and HTKS.

Adobe will no longer be supporting Flash Player after 31 December 2020 and Adobe will block Flash content from running in Flash Player beginning 12 January 2021. Therefore it is not possible to access the Nexperia ePCN-tool anymore. Please use the below link to access related documentation to this change notification:

https://gcm.nexperia.com/change-notification-epcn/SQR_PCN_202101001F01U01_Nexperia.pdf Why do we Implement this Change

Shortage of HD4100 material creates supply safety risk therefore the change is effective immediately. Rejection of this change creates risk to stop supply after change implementation date. Identification of Affected Products

Identification of products is given by Lot number on package box.

Product Availability

Sample Information

Samples are available upon request

HD4100 material will be shipped immediately after Nexperia release criteria, incl. reliability, are fulfilled. Samples will be produced only on request with priority given to fulfill product demand.

Production

Planned first shipment 22-Mar-2021

Update Information

In reference to PCN 202101001F01 (2nd source Polyimide material) we herewith inform you that the effective date for the implementation and date of first shipment will be changed to March 22nd, 2021.

Impact

No impact to the product's functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

2nd sourcing in addition to released material.

Additional information

Timing and Logistics

Your acknowledgement of this change, conform JEDEC J-STD-046, is expected till 22-Mar-2021. Lack of acknowledgement of the PCN constitutes acceptance of the change.

Contact and Support

For all Quality Notification content inquiries, please contact your local Nexperia Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly: **e-mail address** <u>PCN-Bipolar.Discretes@nexperia.com</u> In case of distribution, please contact your distribution partner.

At Nexperia B.V. we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

About Nexperia B.V.

We at Nexperia are the efficiency semiconductor company. We deliver over 90 billion products a year and as such service thousands of global customers, both directly and through our extensive network of channel partners. We are at the heart of billions of electronic devices in the Automotive, Mobile, Industrial, Consumer, Computing, and Communication Infrastructure segments.

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